

## ***PRESS RELEASE***

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### **New AdvancedTCA Backplane Offers Significant Performance Boost at Reduced Cost**

#### ***Bustronic and Z-Plane Demo Samples at ATCA Summit in Santa Clara***

FREMONT, California, Oct 27, 2009 – Elma Bustronic Corporation, an industry leading designer and manufacturer of high performance backplanes, and Z-plane Inc, a high-speed electronic packaging and interconnection technology company, will be exhibiting samples of the high-speed ATCA backplane with Z-plane Links at the ATCA Summit in Santa Clara CA Oct 27-29.

The Bustronic ATCA backplane with links offers up to triple the performance of traditional versions of the architecture at a reduced cost. This is achieved using the Z-plane Links which carry the high speed signals with long traces via a small PCB board that plugs directly into the rear of the backplane. The basic clock signals and shorter trace lines are left on the backplane. This orthogonal link approach allows the backplane to have only 6-8 layers, compared to a traditional ATCA backplane may have 18-24 layers or higher. Characterization studies confirm that the signal integrity of the backplane with the Z-plane Links can produce solid results at higher data rates than conventional backplanes.

The ATCA community is moving to 40 Gigabit/second speeds per channel across the backplane. The version with the Z-plane Links may help ATCA backplanes achieve these very high performance levels, while keeping costs low. The Z-plane Links feature an adapter with guide pins used to firmly secure the rear plane PCB in place and provide strain relief. This adapter has a short, impedance-matched connection between the rear “Z dimension” PCB (or Link) and the backplane connector. They also have staggered arrays, so they can be stacked adjacent to one another, and they come in press-fit pin or compliant pin termination depending on the backplane thickness.

Contact Bustronic at [sales@bustronic.com](mailto:sales@bustronic.com) or visit [www.z-planeinc.com](http://www.z-planeinc.com) for more information.

#### **About Elma Bustronic:**

Founded in 1989, Elma Bustronic specializes in the design and manufacture of high-performance backplanes. Elma Bustronic has a complete line of industry-standard backplanes, including CompactPCI, VME, VME64x, H.110 CT, VXI, VXS, and ATCA. Elma Bustronic’s custom design service combines creative engineering, highly sophisticated computer simulation and modern design techniques to offer customized backplanes that meet the most specialized system requirements. A member of the ELMA Electronic group, Elma Bustronic is located in Fremont, California. Elma Bustronic is a member of PICMG™, VITA, and the StarFabric Trade Association and can be found on the World Wide Web at [www.Bustronic.com](http://www.Bustronic.com).

#### **About Z-Plane, Inc.:**

Founded in 2008, Z-Plane™ Inc is a technology-based high-speed electronic packaging and interconnection technology company, which has been established to develop, market, and manufacture high-speed backplane interconnection solutions. Z-Plane™ Inc was founded to provide new packaging technology for high-speed telecommunications and computing equipment, including routers, servers, and switches with data rates from 40 Giga-bits per second per channel (Gb/sec/ch.) to more than 100 Gb/sec. The Z-Plane™ packaging technology focuses on chip-to-chip interactions and includes the backplane design, the backplane connectors, and the daughter card design. [www.z-planeinc.com](http://www.z-planeinc.com)